OAK-MITSUI *Performance Copper Foils*

MITSUI KINZOKU CORPORATE GROUP

MITSUI KINZOKU

MultiFoil™

Introduction

OAK-MITSUI offers a family of resin coated copper products called MultiFoil. These products are utilized for high-density microvia applications including Build-Up-Multilayer (BUM).

Benefits

- Thin copper and glass free resin allows laser drilling of microvias
- Via holes in the core can be filled simultaneously by the resin from MultiFoil
- Utilize Conventional Lamination Process
- High reliability is assured with excellent peel strengths and high heat resistance

Resin Type	Resin Thickness	Copper Foil	Copper Thickness
MR500 MR600	30 microns 50 microns 65 microns 80 microns	VLP HTE MicroThin™	18 microns 12 microns 5 microns 3 microns

Properties	Unit	MR500	MR600
Glass Transition (Tg)	DMA	150°C	185°C
Dielectric Constant (Dk)	1 GHz	3.4	3.4
Dissipation Factor (Df)	1 GHz	0.025	0.023
Peel Strength B at room Temp	lbs/in	7.2	6.1
S4 (260°C x 20 sec)	lbs/in	7.2	6.1
Flame Resistance		UL94-V0	UL94-V0

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